2SD0874, 2SD0874A (2SD874, 2SD874A)

Silicon NPN epitaxial planer type

For low-frequency power amplification Complementary to 2SB0766 (2SB766) and 2SB0766A (2SB766A)

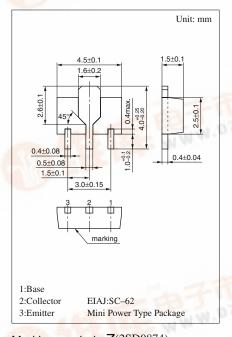
Features

- Large collector power dissipation P_C.
- Low collector to emitter saturation voltage V_{CE(sat)}.
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to	2SD0874	V	30	V	
base voltage	2SD0874A	V_{CBO}	60	77	
Collector to	2SD0874	X.	25	56.00	
emitter voltage	2SD0874A	V_{CEO}	50	V	
Emitter to base voltage		V_{EBO}	5	V	
Peak collector current		I_{CP}	1.5	A	
Collector current		I_C	1	A	
Collector power dissipation		${P_C}^*$	1	W	
Junction temperature		T_{j}	150	°C	
Storage temperature		T_{stg}	−55 ~ +150	°C	

^{*} Printed circuit board: Copper foil area of 1cm² or more, and the board thickness of 1.7mm for the collector portion



Marking symbol: Z(2SD0874) Y(2SD0874A)

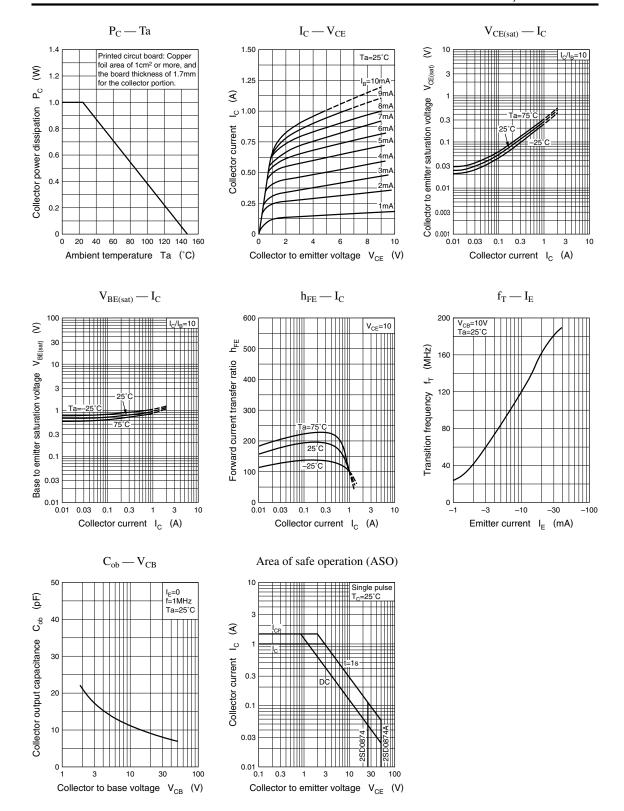
Electrical Characteristics (Ta=25°C)

Paramete	er	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current		I_{CBO}	$V_{CB} = 20V, I_E = 0$			0.1	μΑ
Collector to base	2SD0874	***	I 100A I 0	30			V
voltage	2SD0874A	V_{CBO}	$I_C = 10\mu A, I_E = 0$	60			
Collector to emitter	2SD0874	V _{CEO}	$I_C = 2mA, I_B = 0$	25	- 176		v
voltage	2SD0874A			50		- W	
Emitter to base voltage		V _{EBO}	$I_E = 10\mu A, I_C = 0$	5			V
Forward current transfer ratio		h _{FE1} *1	$V_{CE} = 10V, I_{C} = 500 \text{mA}^{*2}$	85	160	340	
		h _{FE2}	$V_{CE} = 5V, I_C = 1A^{*2}$	50			
Collector to emitter saturation voltage V _{CE(sat)}		V _{CE(sat)}	$I_C = 500 \text{mA}, I_B = 50 \text{mA}^{*2}$		0.2	0.4	V
Base to emitter saturation voltage V _{BE(sat)}		V _{BE(sat)}	$I_C = 500 \text{mA}, I_B = 50 \text{mA}^{*2}$		0.85	1.2	V
Transition frequency		f_T	$V_{CB} = 10V, I_E = -50mA, f = 200MHz$		200		MHz
Collector output capacitance		C _{ob}	$V_{CB} = 10V, I_E = 0, f = 1MHz$			20	pF

^{*1}h_{FE1} Rank classification

TEI				
Ra	Rank		R	S
D FILE PILE	El	85 ~ 170	120 ~ 240	170 ~ 340
Marking	2SD0874	ZQ	ZR	ZS
Psymbosc.c	○2S D0874A	YQ	YR	YS

^{*2} Pulse measurement



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